

DECLARATION OF COMPLIANCE

RoHS Declaration



Eclipse Microdevices Inc. U.S.A., declares that its semiconductor and other RF/Microwave products (including homogeneous sub-components –pins, casing, and internal parts) are designed to be:

- RoHS compliant and meet the requirements defined under Directive 2011/65/EU of the European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) – recast and its amendments¹:

RoHS Restricted Substance	Allowable Limit(s)
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	100 ppm (0.01 weight %)
Hexavalent chromium and its compounds	100 ppm (0.01 weight %)
Lead and its compounds	100 ppm (0.01 weight %)
Polybrominated biphenyls (PBB)	100 ppm (0.01 weight %)
Polybrominated diphenyl ethers (PBDE)*	100 ppm (0.01 weight %)
Bis(2-ethylhexyl) phthalate (DEHP)**	100 ppm (0.01 weight %)
Butyl benzyl phthalate (BBP)**	100 ppm (0.01 weight %)
Dibutyl phthalate (DBP)**	100 ppm (0.01 weight %)

* This includes also DecaBromoDiphenylEther (Deca-BDE).

** In accordance with amendment under Commission Delegated Directive (EU) 2015/863 of 31 March 2015 which becomes effective from 22 July 2019.

Eclipse MDI RoHS compliant semiconductor and other RF devices contain no more than 0.1% lead (Pb) by weight per homogeneous material, or else the devices may contain lead (Pb) for uses allowed by the RoHS Directive, as amended. Eclipse MDI might use any of the following RoHS exemptions for RoHS compliant RF devices:

RoHS Exemption	RoHS Exemption Description
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7(b)	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Any semiconductor and other RF devices that Eclipse MDI has not certified as RoHS compliant, will contain lead (Pb) in solders. These products would be RoHS compliant when used in OEM applications covered by the RoHS exemption 7(b) that permits lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling or transmission, as well as network management for telecommunications.

To facilitate customer requirements and to verify Eclipse MDI product compliance, Eclipse MDI material content information is available by contacting the Eclipse MDI ECO-Products team at quality@eclipsemdi.com

In determining the RoHS status of its products, Eclipse MDI relies upon its suppliers' material content data certification for each homogenous material in the product(s) that they or their subcontractors provide. The signature below verifies that statements above, including but not limited to material composition data are valid and accurate to the best of our knowledge for Eclipse MDI products in original sale condition.

Niall Smyth
Quality Manager - ECO Products
Eclipse MDI

¹ Including latest amendment under Commission Delegated Directive (EU) 2019/172 of 16 November 2018, regarding exemption 15 for lead in solders.